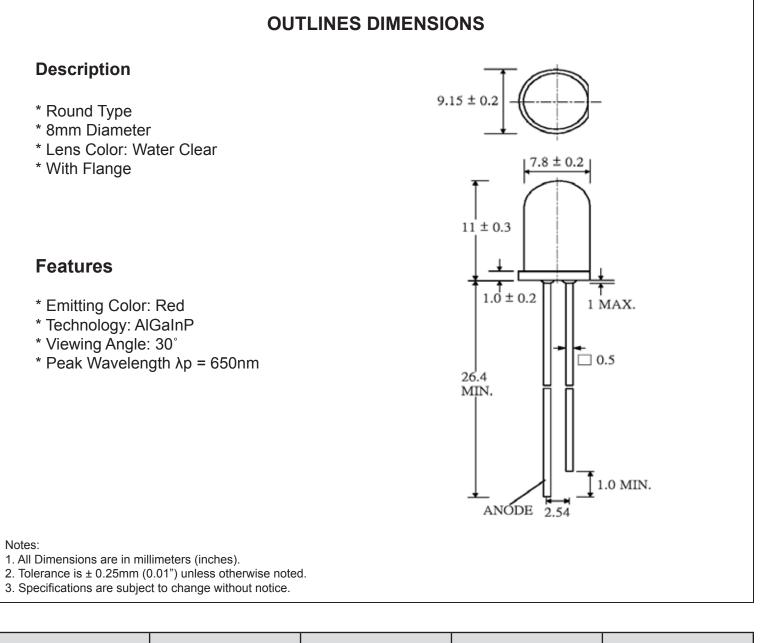


SPECIFICATIONS



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CL78R2C	AlGaInP	Red	Water Clear	30°



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CL78R2C



ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	Po	72	mW
Pulse Current Forward Current	IFP	150	mA
Continuous Forward Current	lf	30	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40~+85	°C
Storage Temperature Range	Тѕтс	-40~+85	°C
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10	Condition: 260 °	C/ 5sec	

OPTICAL-ELECTRICAL CHARACTERISTICS

Value **Test Condition** Parameter Symbol Unit Min Тур Max 550 1100 Luminous Intensity I_F = 20mA Iv _ mcd Forward Voltage I⊧ = 20mA 1.95 2.4 VF V _ **Reverse Leakage Current** $V_R = 5V$ IR 10 μA -_ **Viewing Angle** $2\theta 1/2$ I_F = 20mA 30 deg _ _ 650 Peak Wavelength I_F = 20mA λP _ nm _ Dominant Wavelength 630 λD I_F = 20mA nm _ _ 22 Spectral Line half-width I_F = 20mA Δλ _ nm _

*Tolerance of viewing angle: -10 / +5 deg.



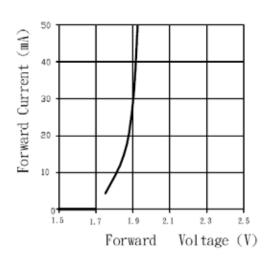
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(TA=25°C)

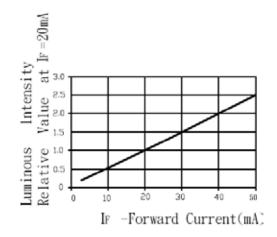


OPTICAL CHARACTERISTIC CURVES

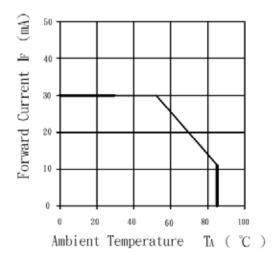
Forward Current vs. Forward Voltage



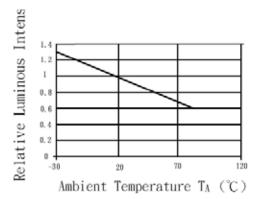
Relative Intensity vs. Forward Current



Forward Voltage vs. Ambient Temperature



Relative Intensity vs. Ambient Temperature





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SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering					
	3mm Series	Others			
Temperature Soldering Time	300 °C Max	350 °C Max			
Position	3 Second Max	3 Second Max			
FOSILION	No closer than 3mm from the	No closer than 3mm from the			
	base of the epoxy	base of the epoxy			

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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